AN8133FHP (Under development)

High Speed Low Power Consumption Bi-CMOS 10-Bit A/D Converter

Overview

The AN8133FHP is a 10-bit A/D converter for image processing which employs the Bi-CMOS process to realize the low power consumption.

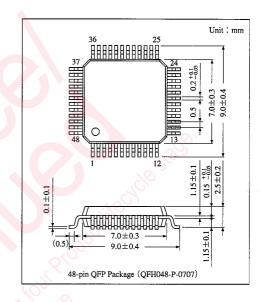
Features

- 10-bit resolution
- Maximum conversion rate: 40 MSPS (min.)
- Low power consumption: 200 mW (typ.)
- Operation on single power supply of 5 V
- S/H circuit not required
- Input/Output form: TTL level compatible

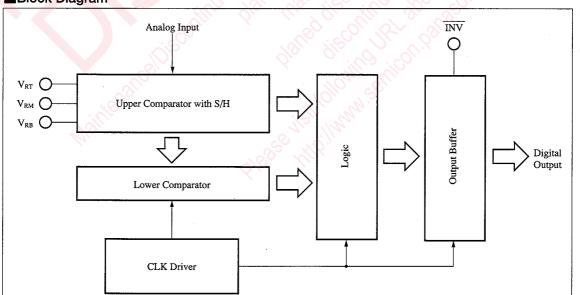
■ Application Field

- Digital video broadcasting such as D-STB
- Image equipment such as HDTV
- OA equipment such as image scanner
- · Medical equipment such as ultrasonic diagnosis device

Note) Since the AN8133FHP is under development, the description here may be modified without any prior notice. When the final design is reviewed, refer to the up-to-date product standards.



Block Diagram



and D/A

Absolute Maximum Rating (Ta=25%)

Parameter	Symbol	Rating	Unit	
Supply voltage	V _{cc}	-0.5 to +6.0	v	
Analogue input voltage	V _{IN}	0 to V_{CC} \pm 0.3	v	
Digital input voltage	V _{CLK}	-0.5 to $V_{CC}+0.5$	V	
Digital output current	I _{OVF} /I _{D0} to I _{D9}	-15	mA	
Reference voltage	V _{RT} /V _{RB}	0 to V _{CC} +0.5	V	
Power dissipation	P _D	700 (Ta=75°C)	mW	
Operating ambient temperature	T_{opr}	0 to 75	°C	
Storage temperature	T _{stg}	-55 to +150	C	

■ Recommended Operating Conditions (Ta=25°C)

Parameter	Symbol	Condition	min	typ	max	Unit
Supply voltage	V _{cc}		4.75	5.0	5.25	V
Deference veltage	V _{RT}			4.25		V
Reference voltage	V_{RB}			2.25	_	V
Analogue input voltage	V _{IN}		V_{RB}	_	V_{RT}	V
Dirichly and	$V_{ m IH}$		2		4	V
Digital input voltage	V_{IL}	030	<u> </u>		0.8	V
Digital autuut aumant	I_{OH}	$V_{OH}=2.7V$		-0.4		mA
Digital output current	I_{OL}	$V_{OL} = 0.4V$		1.6		mA
Clock input pulse width		0, 0		50	_	%

■ Electrical Characteristics (V_{CC}=5V, Ta=25°C)

Parameter	Symbol	Condition	min	typ	max	Unit
Supply current	I_{CC}	190 11/10 00 00		40	· =	mA
Reference resistive current	I_{RT}	V _{RT} =4.25V	~1 0° .	2.4	0.77	mA
Reference resistive current	I_{RB}	V _{RB} =2.25V	12	-2.4	?	mA
Input bias current	I_{IN}	$V_{IN}=3.2V$	1	· Ch.	150	μ A
Clark investment	I_{IH}	V _{CLK} =2.7V	25	1		μΑ
Clock input current	I _{IL}	V _{CLK} =0.4V	(0)	1		μ A
District	V _{OH}	$I_{OH} = -400 \mu A$	2.7	3.4		V
Digital output voltage	V _{OL}	I _{OL} =1.6mA	٧		0.4	V
Linearity error	EL	$V_{IN}=2V_{P-P}$		±1		LSB
Differential linearity error	E _D	$V_{IN}=2V_{P-P}$	· —		1.0	LSB
Maximum conversion rate	F _C	$V_{IN}=2V_{P-P}$	40	_		MSPS
Overstination	CAT	f_{CLK} =40MHz, f_{IN} =1MHz		55		dB
Quantization noise	5/N	S/N $\frac{f_{CLK} = 40MHz, f_{IN} = 1MHz}{f_{CLK} = 40MHz, f_{IN} = 15MHz} - 55$		dB		
Difference gain	DG	IRE standard 15Kz Sawtooth 40% subcarrier		0.5	1.0	%
Differential phase	DP	f _{CLK} =20MHz, Nolock		0.5	1.0	$^{\circ}$
Input band	BW	$V_{IN}=2V_{P-P}$, $-3dB$	50			MHz
Digital output delay	τ _d	f _{CLK} =40MHz		20		ns
Input capacitance	C _{IN}	V _{IN} =3.25V		10		pF

■ Pin Description

Pin No.	Symbol	Pin name	Standard waveform	Voltage level	Description
42	ĪNV	Digital output invert pin		TTL	Setting INV pin to "L" level inverts all the data outputs (D0-D9) but not the overflow output. This pin is set to "L" level with no connection and operates a synchronously with clock.
24,30 39,40 43,47	DVCC	Digital power supply pin		5V	It is a power supply pin for digital circuit block. Connect tantalum capacitor of several μF and ceramic capacitor of $0.1 \mu F$ as near as possible to this pin between this pin and DGND.
21,23 31,38 41,46	DGND	Digital ground		0V	Connect AGND and DGND with the possible lowest impedance at one point as near as possible to the chip.
37	OVF	Overflow pin		TTL	When overflow occurs, it becomes "H." This pin is not affected by INV pin.
25 26 27 28 29 32 33 34 35 36	D0 D1 D2 D3 D4 D5 D6 D7 D8 D9	Digital output (LSB) Digital output (MSB)	Refer to the timing chart.	TTL	It is an output pin of TTL Level. In order to prevent the digital noise to entering the analogue circuit, suppress the ringing as far as possible.
3,6 8,10 13,15 18,45 48	AGND	Analogue ground		ov	Connect the AGND and DGND with the possible lowest impedance at one point as near as the chip.
11 12 14 16 17	V _{RT} V _{RTS} V _{RM} V _{RBS} V _{RB}	Reference voltage high level, Reference voltage middle point level, Reference voltage low level	luneq iven	4.25V 3.25V 2.25V	It is used to set the reference voltage for comparator. Normally, V_{RT} is given 4.25V and V_{RB} is given 2.25V. Connect tantalum capacitor of several μF and ceramic capacitor of 0.1 μF in parallel between each pin and analogue ground. V_{RM} is provided for linearity compensation, which gives middle point potential between V_{RT} and V_{RB} . However, it is normally opened. V_{RTS} and V_{RBS} are sense pin of V_{RT} or V_{RB} respectively.
9	$V_{\rm IN}$	Analogue input pin		2.25V~4.25V	It is an input pin of analogue signal for A/D conversion circuit.
1,2 7,19 44	AVCC	Analogue power supply pin		5.0V	It is a power supply pin for analogue circuit block. Connect tantalum capacitor of several μF and ceramic capacitor of $0.1\mu F$ as near as possible to this pin between this pin and AGND.
22	CLK	Clock input	Refer to the timing chart.	TTL	It is a clock for sampling. For their timing, refer to the timing chart.

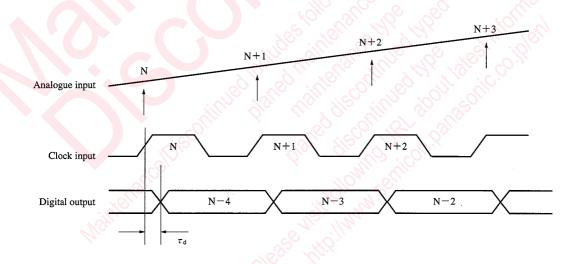
Pin No.4, 5, 20: NC

A/D and D/A Converters

■ Output Code

	Input signal	Digital output			
Step		<u>ī</u> NV=H	<u>INV</u> =L		
	2.000VFS 1.953mV STEP	M L OVF9876543210	M L OVF9876543210		
000	4.250000	0 0000000000	0 111111111		
001	4.248047	0 000000001	0 1111111110		
•	•		•		
•		•	•		
•			•		
511	3.251953.	0 011111111	0 1000000000		
512	3.250000	0 100000000	0 011111111		
513	3.248047	0 100000001	0 0111111110		
•			2,000		
•		•	%° .		
•	•		Ap.		
1023	2.251953	0 111111111	0 0000000000		
1024	2.250000	1 111111111	1 0000000000		

Timing Chart



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